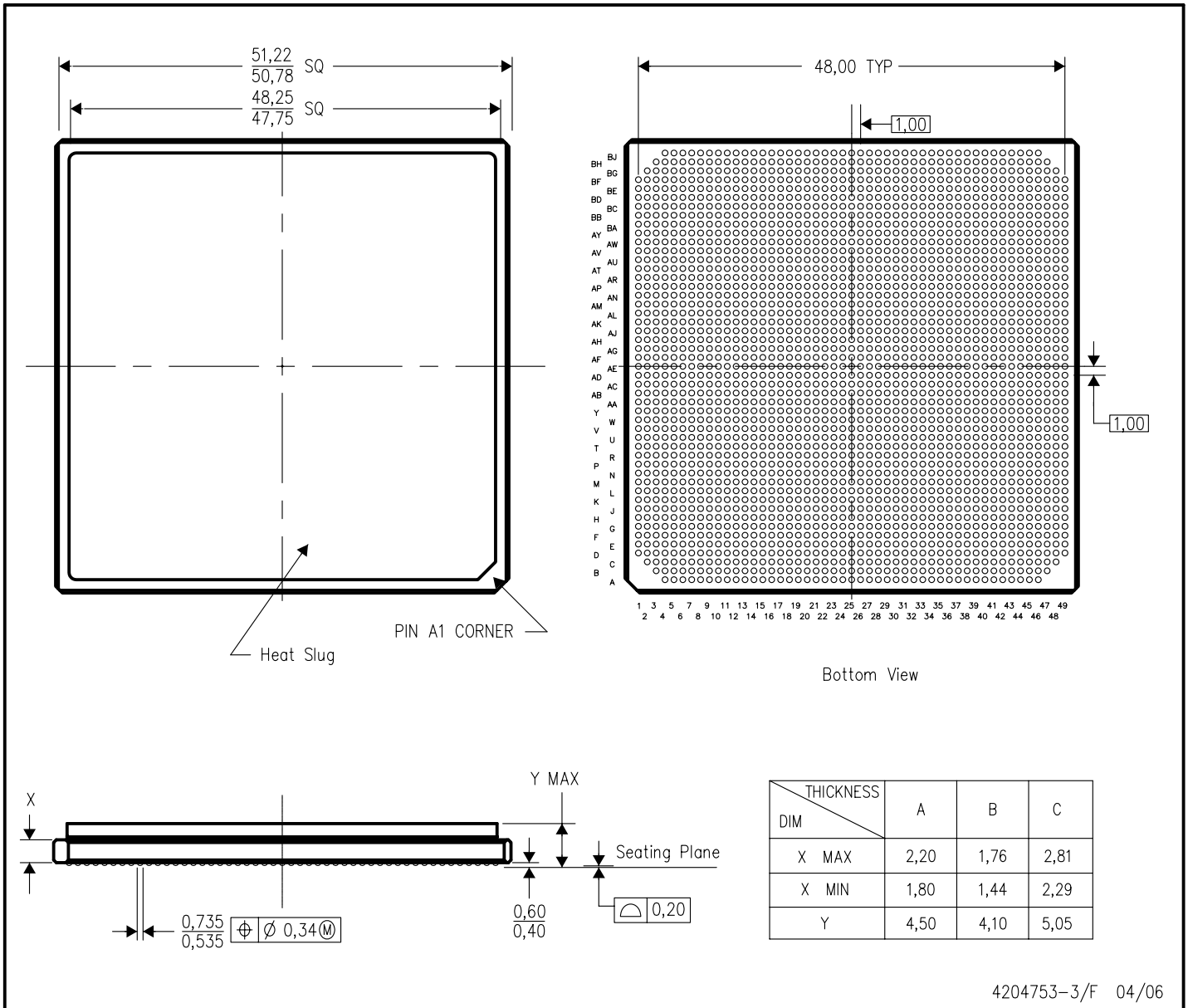


MECHANICAL DATA

GDZ (S-CBGA-N2377)

CERAMIC BALL GRID ARRAY



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Thermally enhanced ceramic package with a heat slug (HSL).
 - Flip chip application only.

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